

## AMENDMENTS TO THE SPECIFICATION

Please replace the paragraph beginning on line 22 of page 11 with the following amended paragraph:

Digitizing element 330 is in contact with and able to conduct electrical current from an electrical trace 331. Whenever conductive layer 320 comes into contact with digitizing element 330, an electrical signal is detected by electrode 312 at a point which can be measured and used as an input signal for device 300. Electrical trace 331 and electrode 312 321 are separated by an insulator 322.

Please replace the paragraph beginning on line 22 of page 11 with the following amended paragraph:

In one embodiment, conductive layer 420 and digitizing element 430 are a conductive paste which is commercially available from Acheson Colloids Company of Port Huron, MI. More specifically, the Electrodag® line of flexible conductive polymers from Acheson Colloids are well suited to be utilized in conductive layer 420 and digitizing element 430. The Electrodag® polymers provide excellent flexibility and adhesion to a wide variety of substrates, as well as a wide range of resistance values. Other conductive paste products that are consistent with the discussions herein could also be used. Conductive layer 420 is in contact with and is able to conduct electrical current to electrode 421 and digitizing element 430 is likewise in contact with trace 431. Electrical trace 431 and electrode 421 are separated by an insulator 422.

Please add the following new paragraph between the paragraph ending on line 8 of page 14 and the paragraph beginning on line 10 of page 14:

Supporting structure 440, in the present embodiment of the invention, may be a rigid molded plastic such as PC, PC/ABS, or ABS and may form a perimeter frame around the top of the electrical device. Supporting structure 440 may be co-molded with outer film 410 to form a single-piece front cover assembly which may form the top surface of device 400. Supporting structure 440 will also provide some method of securely attaching the front cover assembly to a back cover assembly (not shown), thus forming a dust-proof and waterproof enclosure for the internal components of device 400.

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